CLAIMS:

1. – 14. (cancelled)

15. (previously presented) A method for manufacturing an assembly including a printed circuit board and a plurality of tape carrier packages, each having a conductive lead thermocompression bonded to a corresponding conductive land of a corresponding land group on the printed circuit board, the method comprising:

arranging the tape carrier packages along a common axis at respective first intervals;

forming a plurality of the land groups on the printed circuit board, the land groups being arranged along the common axis at respective second intervals determined in accordance with the thermal expansion properties of the printed circuit board such that, in a pre-compression bonded state, the respective second intervals between adjacent ones of the land groups are smaller than the respective first intervals between adjacent ones of the corresponding tape carrier packages;

thermocompression bonding the respective leads of the tape carrier packages to corresponding ones of the lands on the printed circuit board; and,

during the thermocompression bonding, allowing the printed circuit board to expand such that the respective lands are substantially aligned with corresponding ones of the leads of the tape carrier packages.

16. (cancelled)

17. (previously presented) The method of claim 15, further comprising measuring the thermal expansion properties of the printed circuit board before forming the leads thereon.

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18. (previously presented) The method of claim 15, wherein the respective second intervals between adjacent ones of the land groups are asymmetric with respect to a line passing though the middle of a width of the printed circuit board when the printed circuit board is asymmetric with respect to said line.

19. (previously presented) A printed circuit board adapted to be electrically connected to an external device through a plurality of tape carrier packages, each having a conductive lead group, arranged at first intervals, the printed circuit board comprising:

a substrate; and,

a plurality of conductive land groups formed on the substrate and disposed parallel to and spaced apart from each other at second intervals, each land group corresponding to a respective one of the conductive lead groups of the tape carrier packages, wherein the second intervals are respectively smaller than the first intervals.

20. (cancelled)

21. (previously presented) The printed circuit board of claim 19, wherein the second intervals respectively become substantially the same as the first intervals by thermal expansion when the printed circuit board undergoes a thermo-compression bonding process.

22. (previously presented) The tape carrier package of claim 19, wherein the second intervals are asymmetric with respect to a line passing through a midpoint of a width of the printed circuit board when the printed circuit board is asymmetric with respect to said line.

23. (previously presented) A method of manufacturing a printed circuit board that is to be electrically connected to an external device through a plurality of tape carrier packages spaced apart from each other, comprising:

forming printed circuit board land groups that correspond one-to-one with each of the tape carrier packages on a substrate such that intervals between the printed circuit board land groups are respectively smaller than intervals between the tape carrier packages.

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24. (previously presented) The method of claim 23, wherein the interval between the printed circuit board land groups is determined by:

measuring an amount of total thermal expansion of the substrate under a thermo-compression bonding process, and

obtaining the interval between the printed circuit board land groups by considering the amount of total thermal expansion.

25. (previously presented) The method of claim 15, wherein each tape carrier package comprises a group of parallel, spaced conductive leads, and each conductive land group comprises a corresponding group of parallel, spaced conductive lands.

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